

## **Arrangement for Transferring Information/Structures to Wafers**

### **ABSTRACT OF THE DISCLOSURE**

An arrangement for transferring information/structures to wafers uses a stamp on which the information/structures to be transferred have been applied as elevated structures. The wafer is fixed on a chuck and is provided with a plastically deformable auxiliary patterning layer. In various implementations, the dimensions of the stamp approximately correspond to those of the wafer, the stamp is provided with the elevated structures essentially over the whole area, and/or the stamp and the wafer are in each case provided with mutually assigned pairs of alignment marks in such a way that the stamp can be positioned in a predetermined position on the wafer by means of an infrared positioning system and can be pressed into the plastically deformable auxiliary patterning layer.